

## Industrial AI Technology in Manufacturing

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# Today

1 Why Manufacturing AI?

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2 Computer vision ML for manufacturing

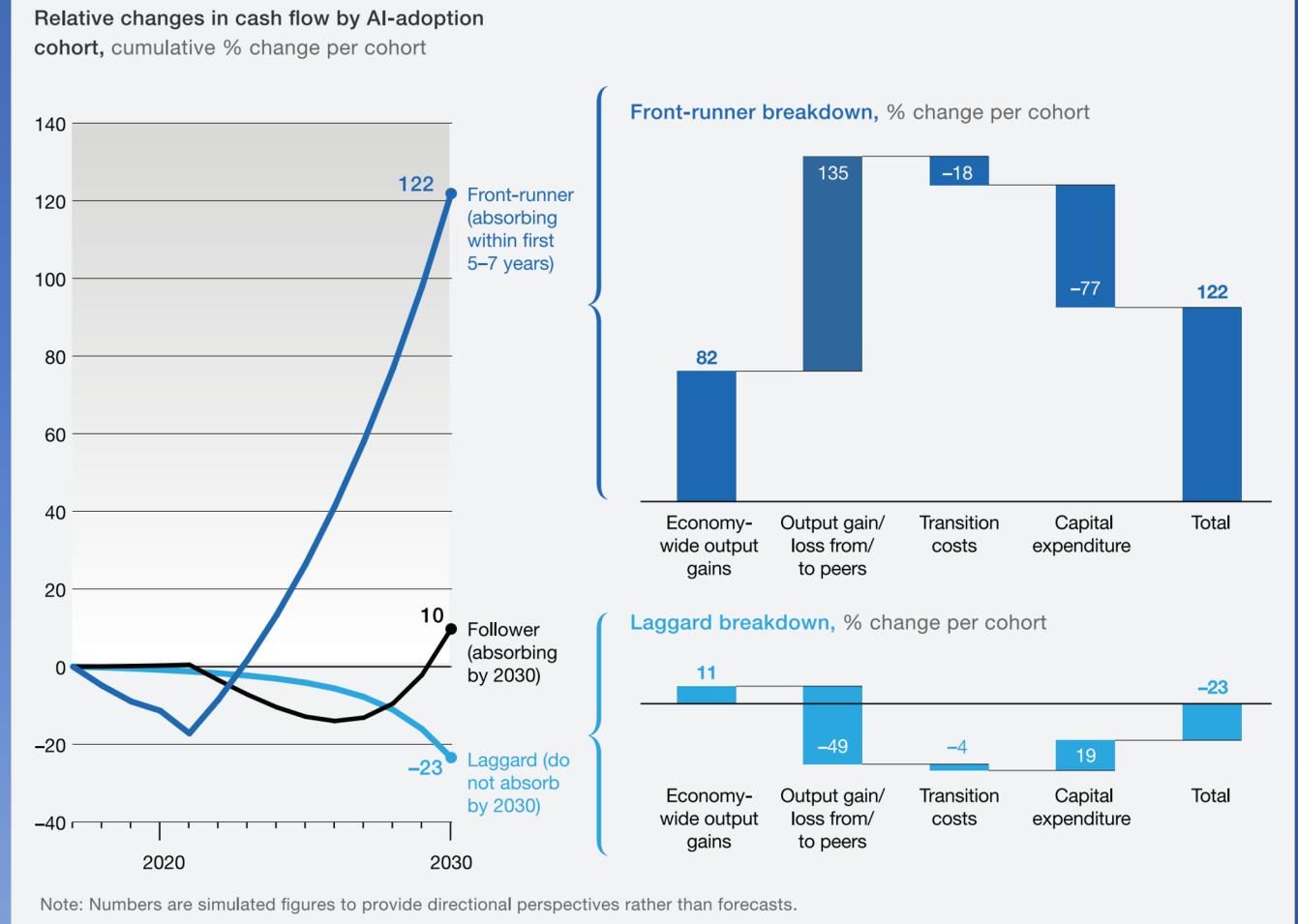
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3 Time-series ML for manufacturing

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4 Difficulties with time-series ML in manufacturing

Fast AI adoption  
WILL create way  
larger economic  
gains



\* Source: McKinsey Global Institute Analysis (2019)

## Data Characteristics

## Virtuous (or Vicious) Cycle

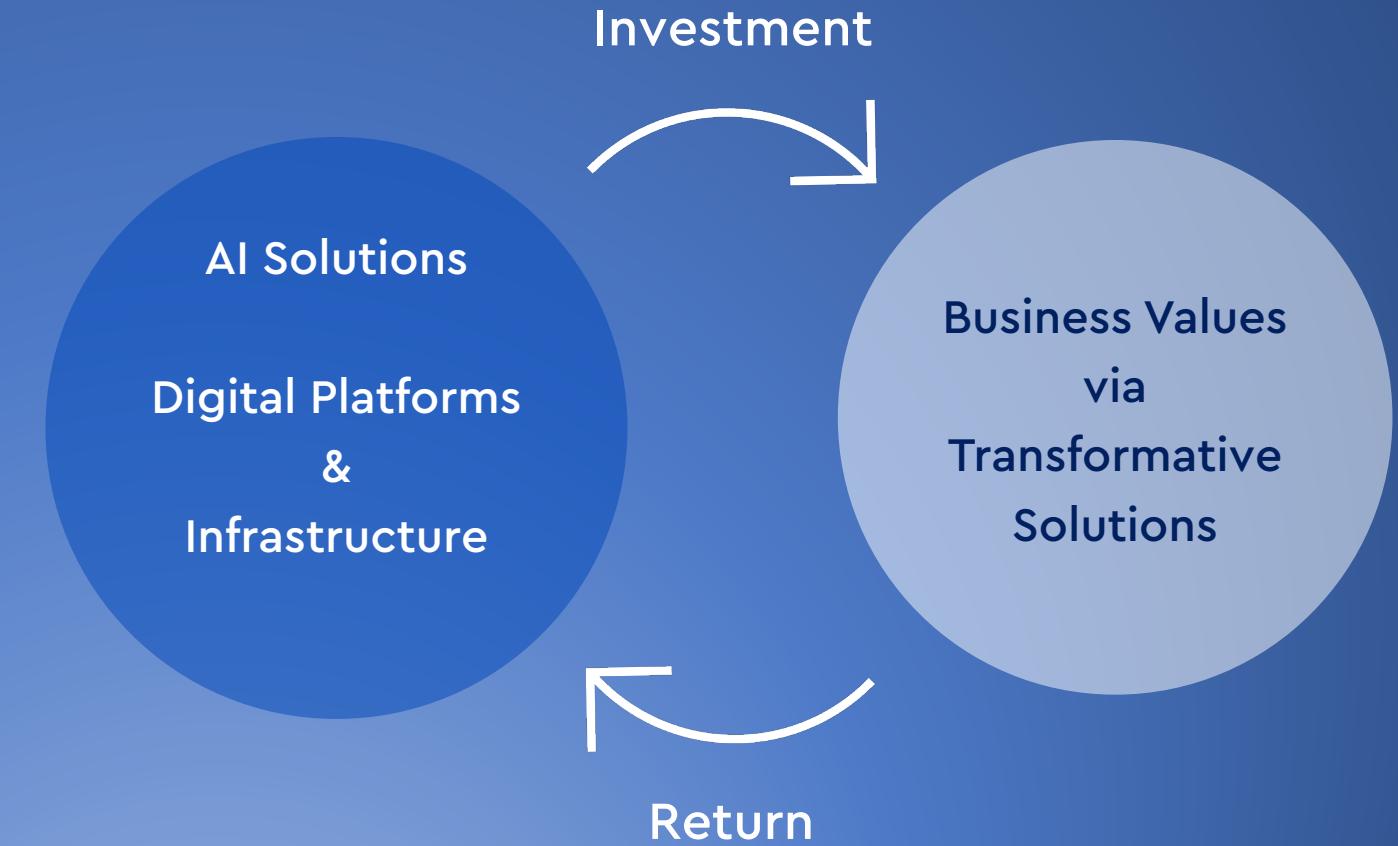
## Data-centric AI



## Data Characteristics

## Virtuous (or Vicious) Cycle

## Data-centric AI



"We need 1,000 models for 1,000 problems" – Andrew Ng

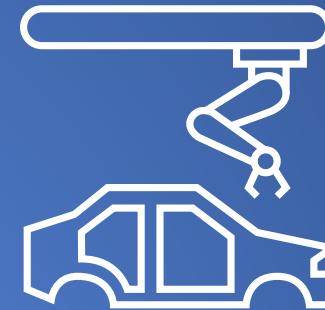
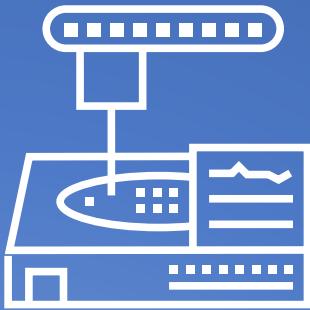
## Data Characteristics

### Virtuous (or Vicious) Cycle

### Data-centric AI

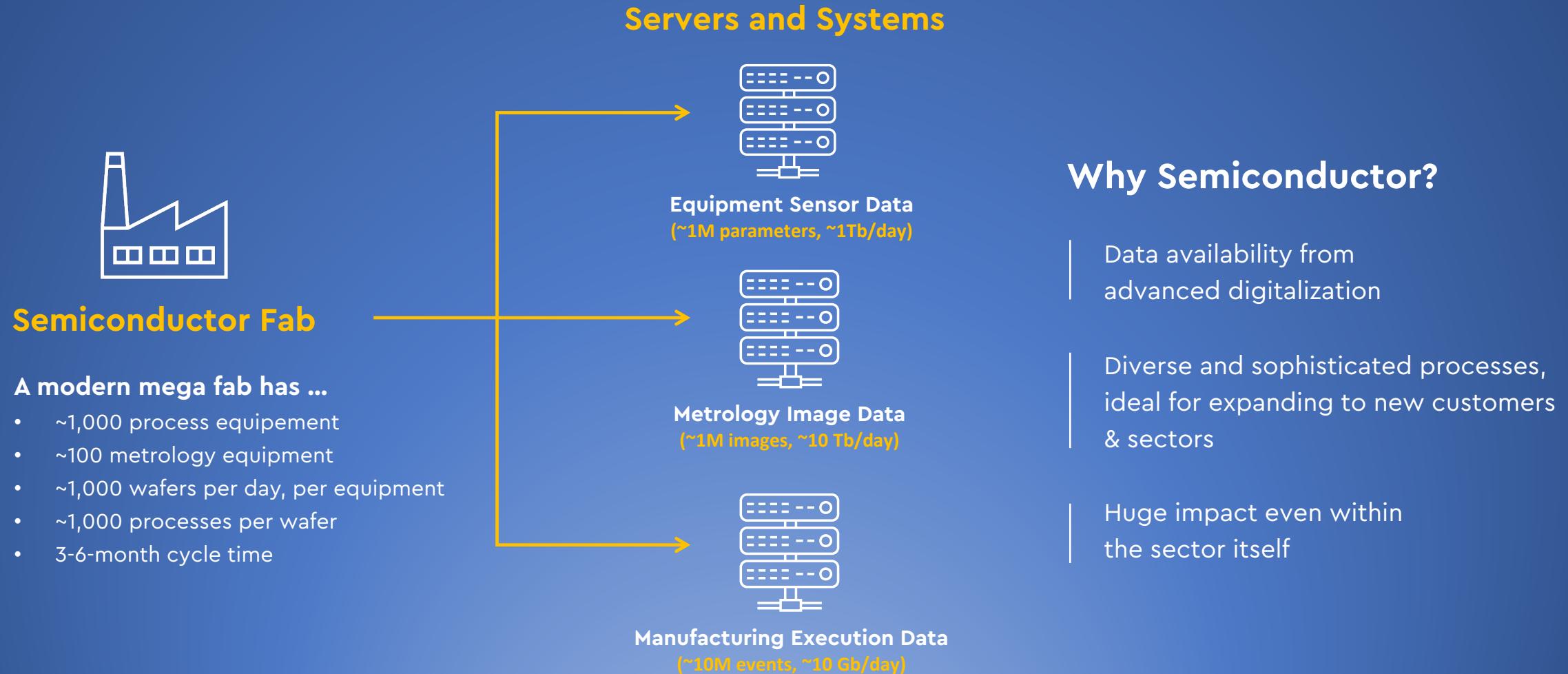
#### Data-centric AI

Discipline of systematically engineering the data used to build an AI system



Every company or sector has its own problems

# Our initial focus for 10x changes\*

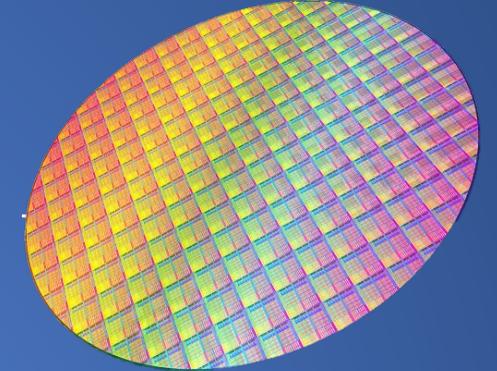


# Computer vision and time-series ML in Manufacturing

## *lots of image data to measure and inspect*

Scanning electron microscope (SEM) images, transmission electron microscope (TEM) images, etc.

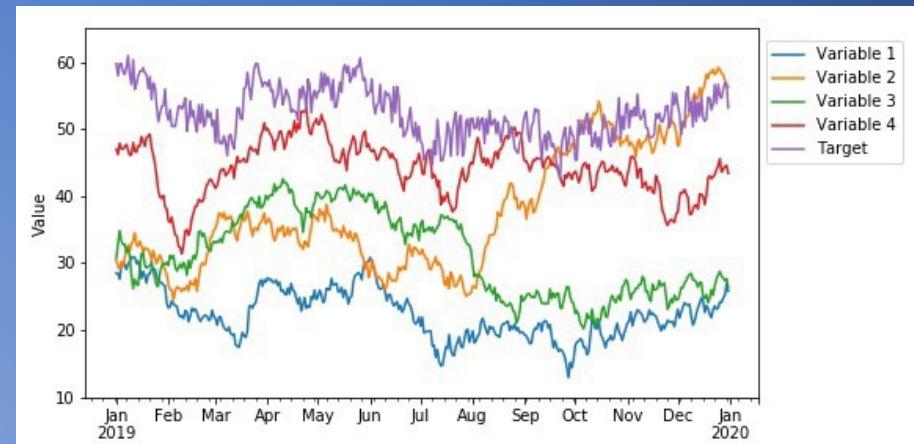
→ Image pattern classification, image anomaly detection, defect inspection, etc.



## *(almost) All the data coming from manufacturing are time-series data*

Equipment sensor data, process times, material measurement, etc.

→ time-series (TS) regression / prediction/estimation, TS anomaly detection, etc.



# Computer Vision ML for manufacturing



## Metrology

*Measurement of critical features*

## Inspection

*Anomaly detection,  
localization and classification*

Image courtesy of ASML

# Scanning Electron Microscope\*

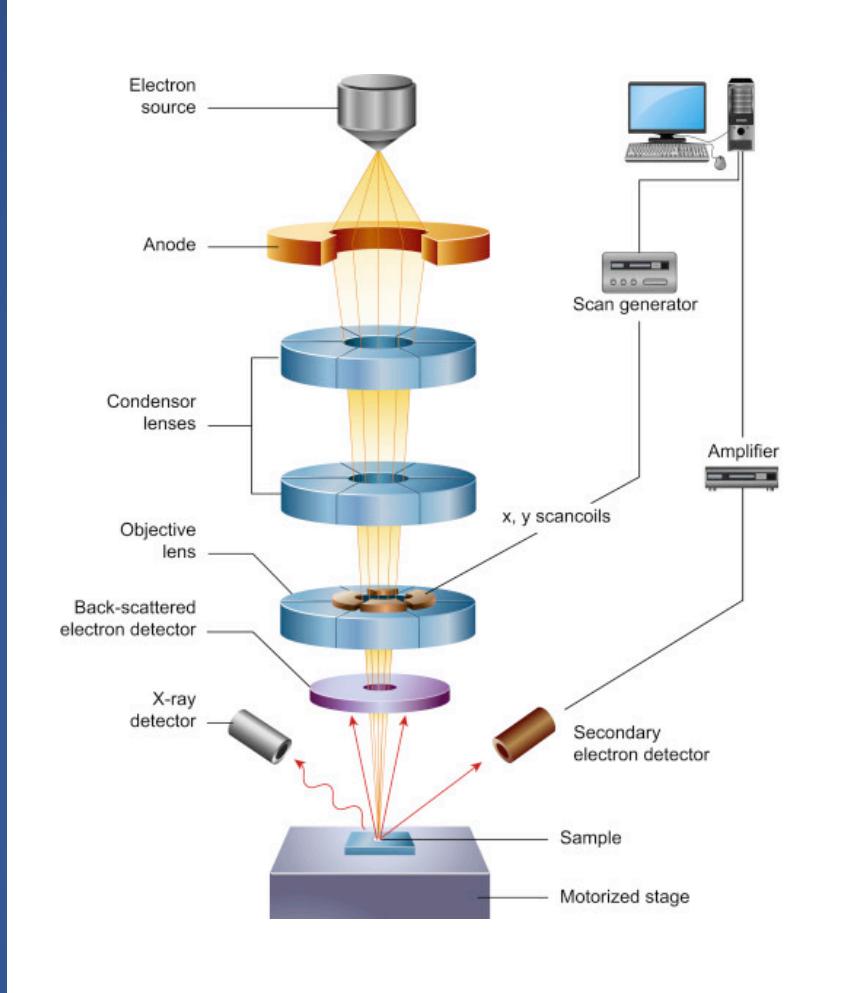
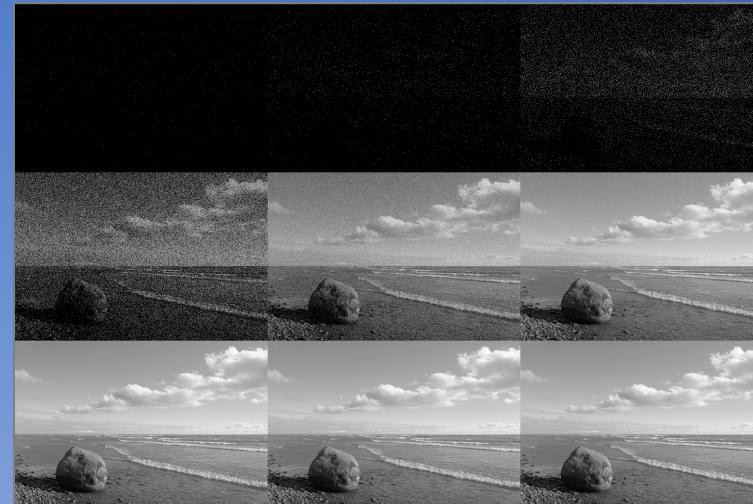
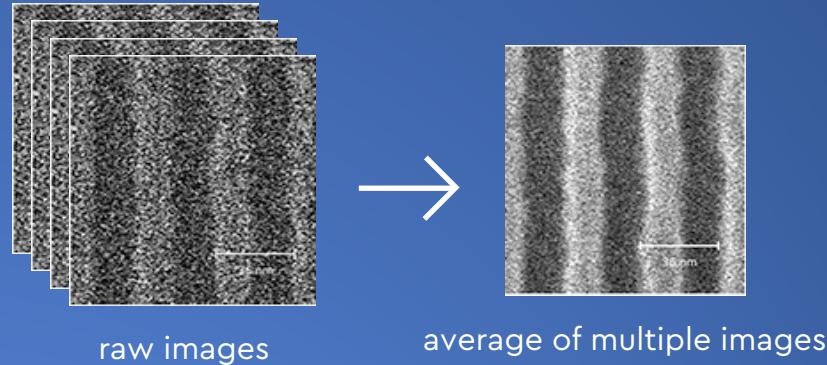


Image courtesy of <https://www.sciencedirect.com/science/article/pii/B978008100040300002X>



Shot Noise Image courtesy of [https://en.wikipedia.org/wiki/Shot\\_noise](https://en.wikipedia.org/wiki/Shot_noise)

# Image restoration

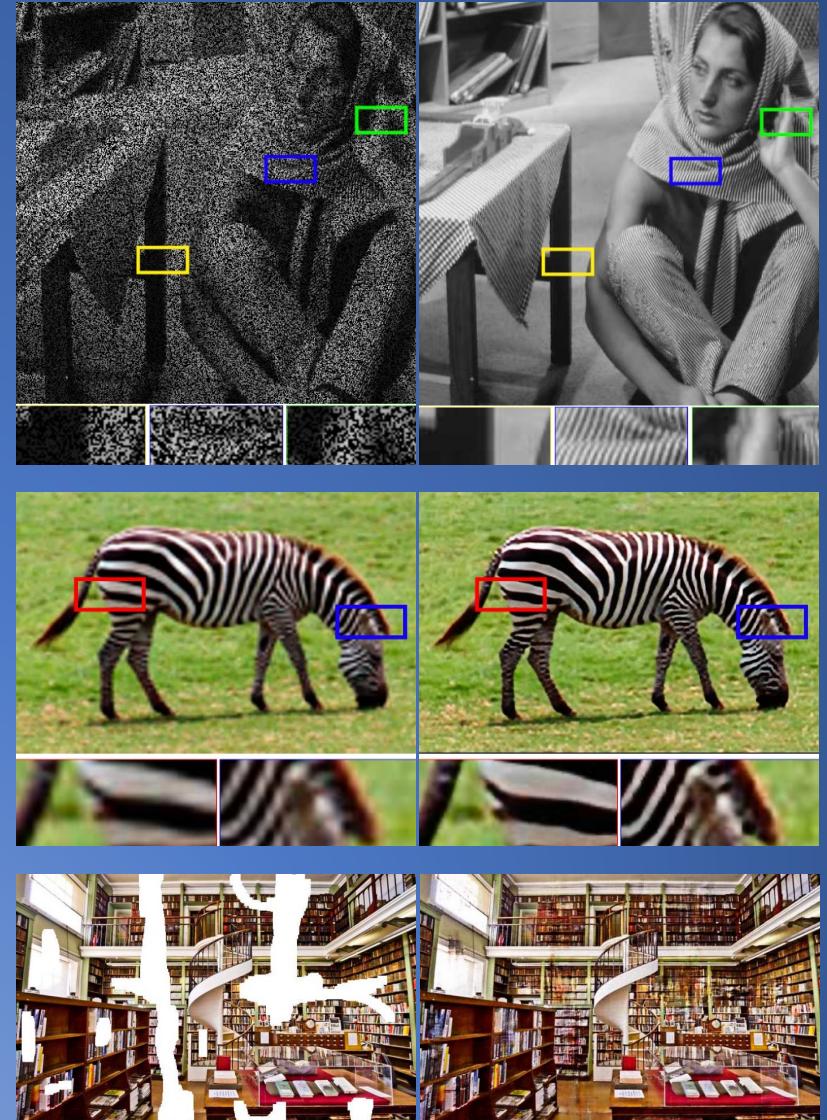
## Inverse problem of image corruption

$$x = f(y) + n$$

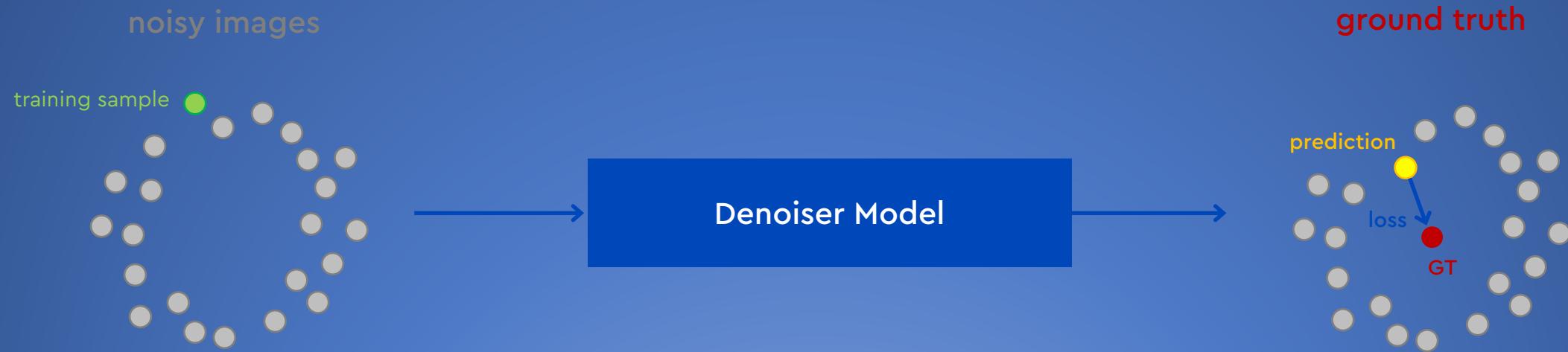
- y: clean image
- x: corrupted image
- n: noise

## $f(\cdot)$ and corresponding solutions

- Noising: Identity function → Denoising
- Downsampling → Super-resolution
- Missing pixels → Inpainting

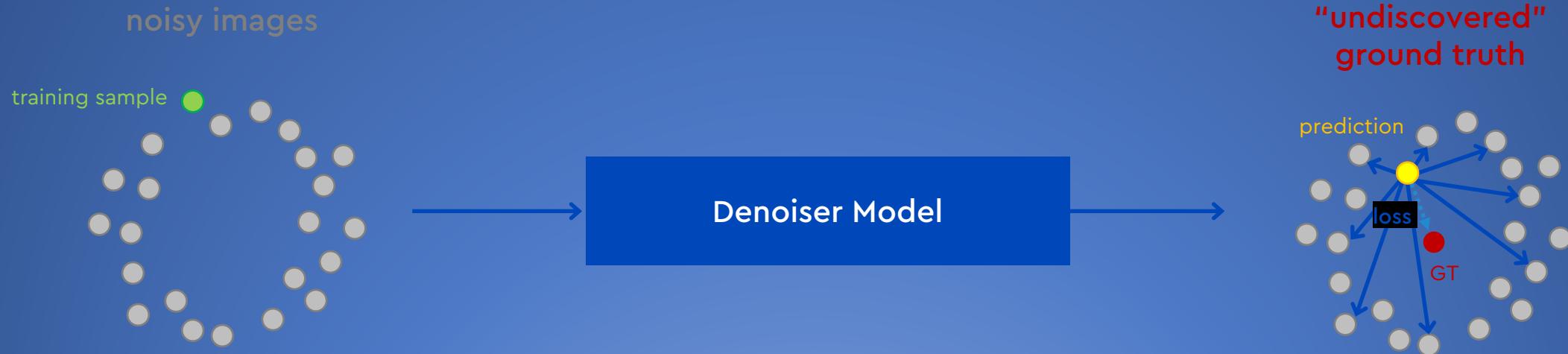


# Supervised image denoising



*However, it is not possible to acquire ground-truth images from SEM device, in practice.*

# Blind denoising without ground truth



*If the mean of the noise is zero, the average of the gradients that model takes is same with the gradient to the ground truth*

# Metrology based on segmentation and pattern recognition

Investment

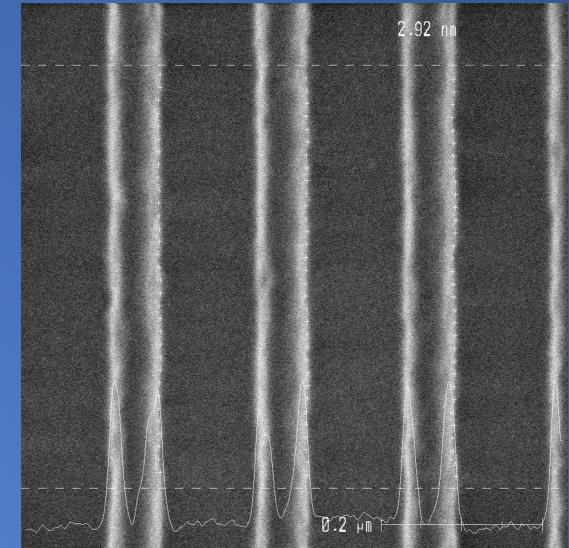
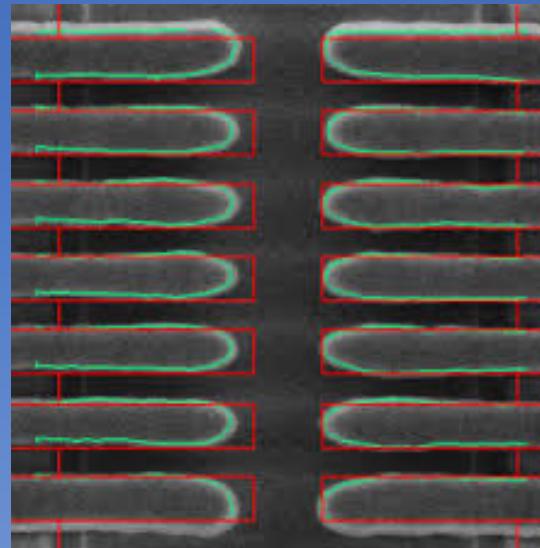
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Automatic measurement of critical dimensions

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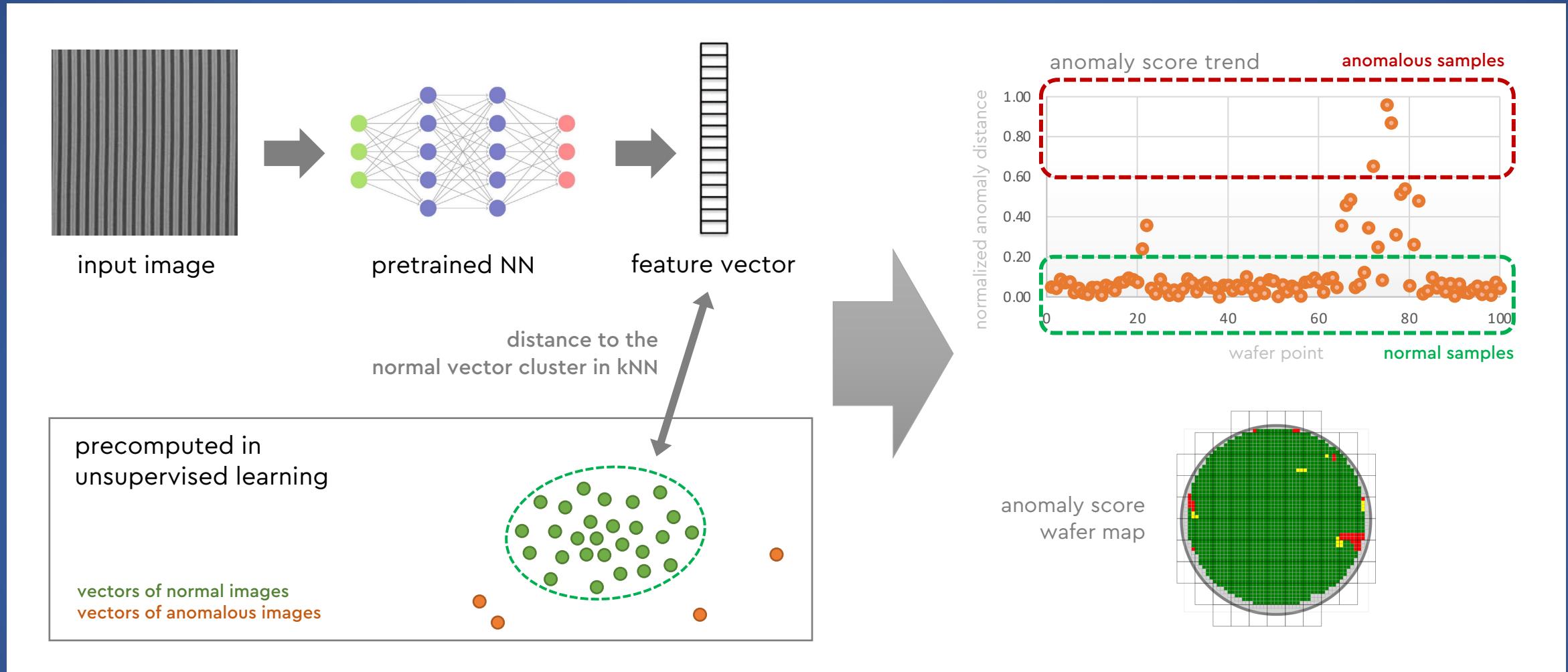
## Approaches

- Unsupervised texture segmentation
- Repetitive pattern recognition

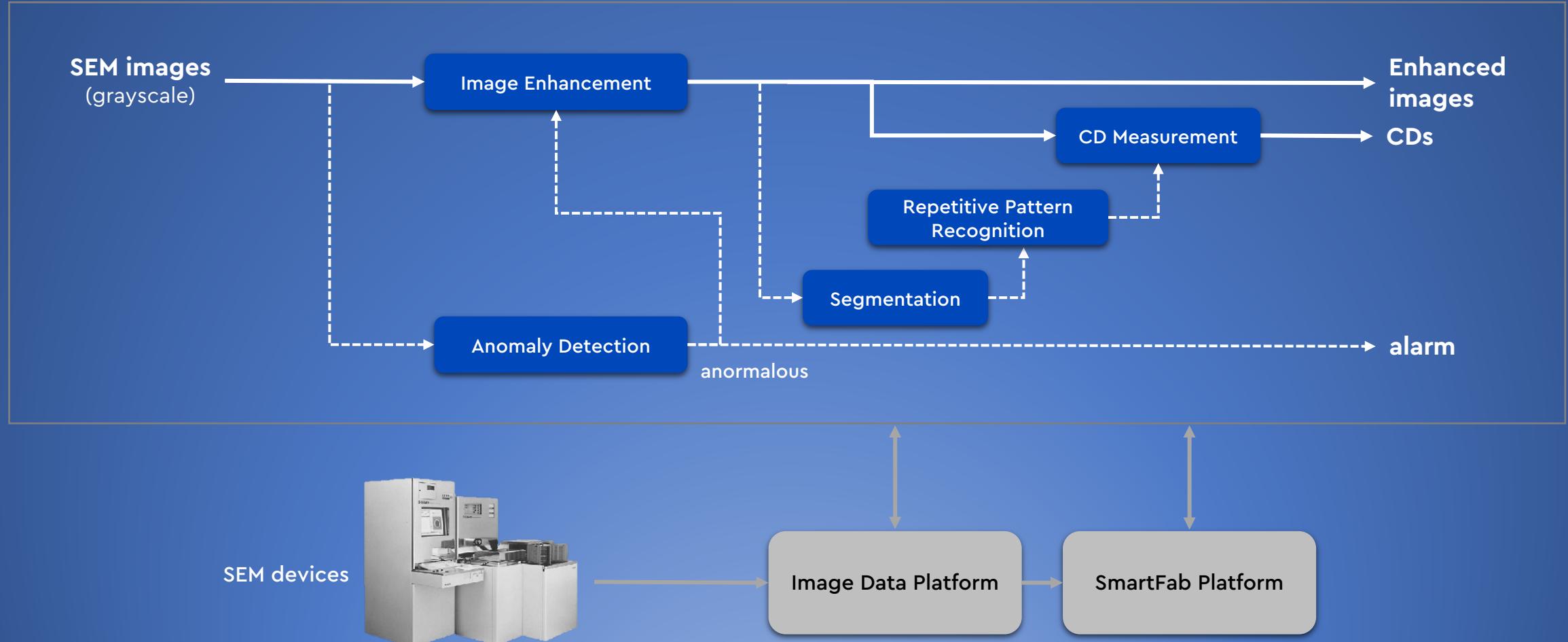


<0.1 nm measurement precision guaranteed

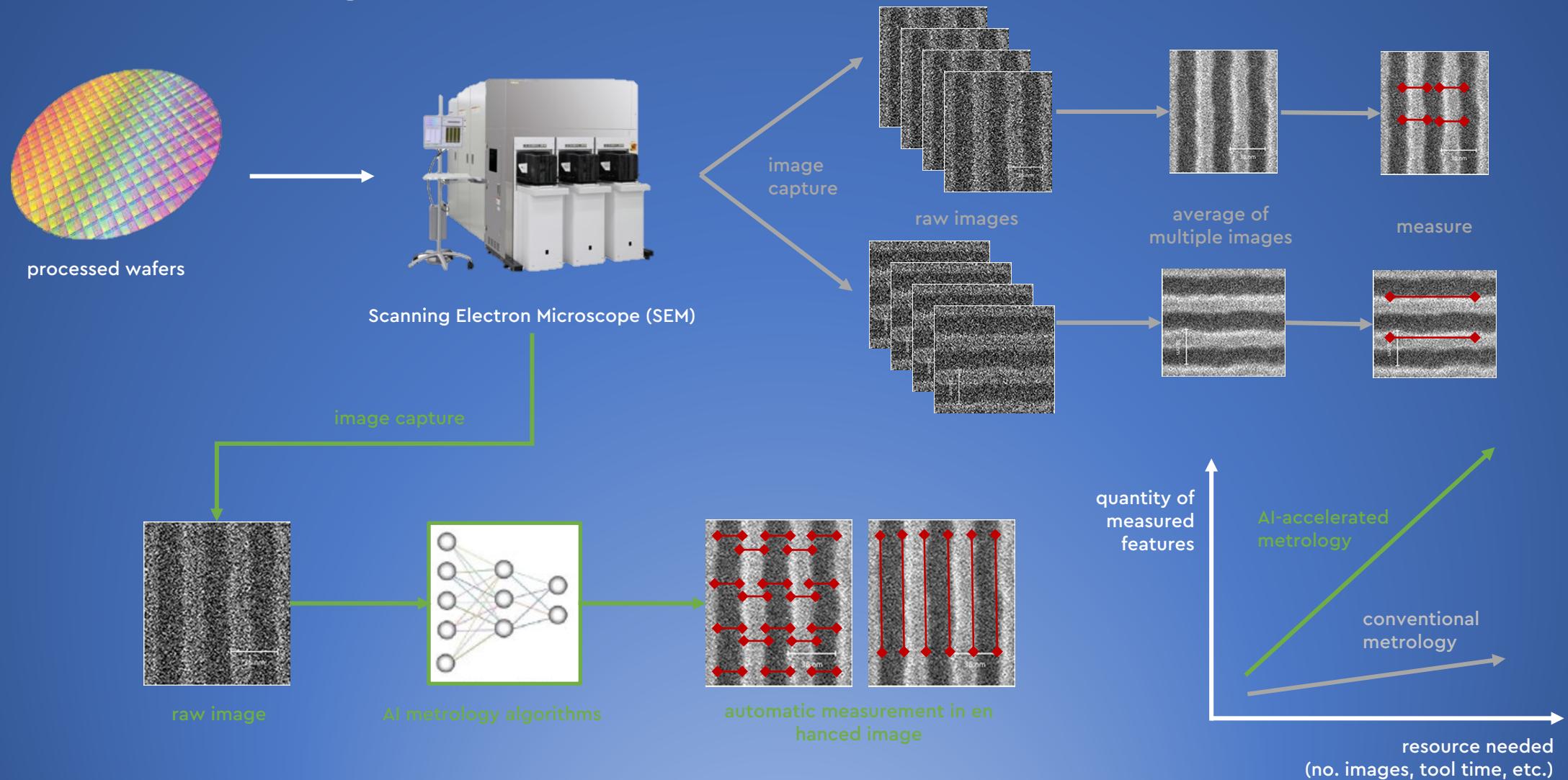
# Anomaly detection in unsupervised learning\*



# AI-accelerated metrology system



# Automatic measurement for semiconductor manufacturing

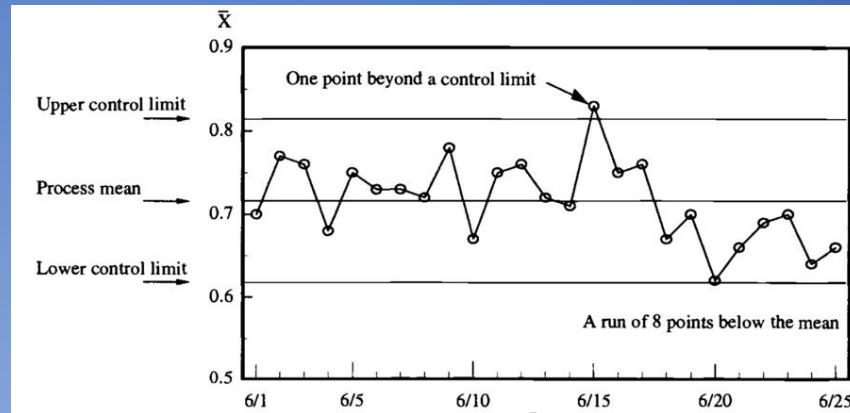
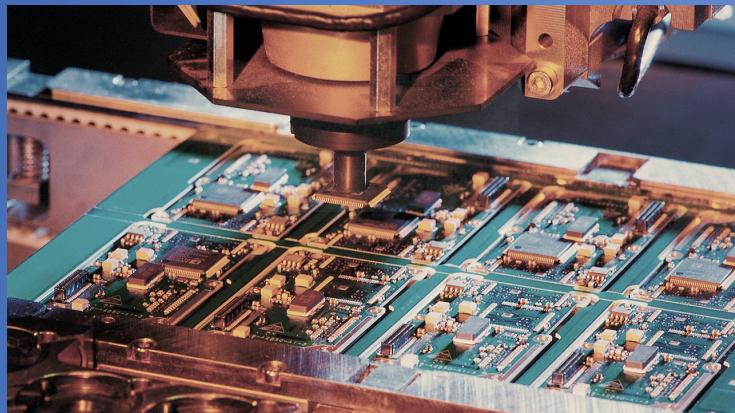


# Time-series ML for manufacturing

# Why time-series ML?

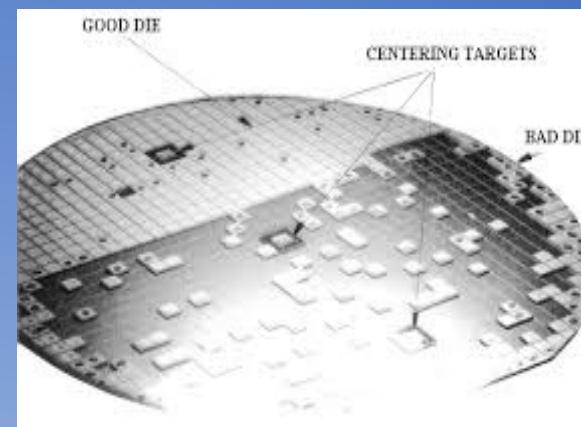
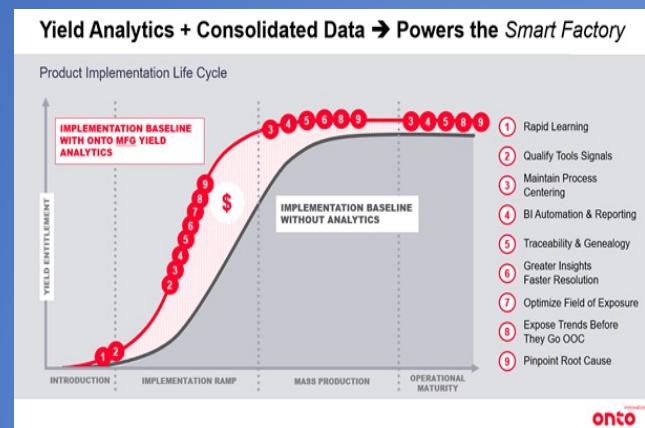
*manufacturing application is about one of the followings:*

- prediction of time-series values - virtual metrology, yield prediction
- classification of time-series values - equipment anomaly alarm generation
- anomaly detection on time-series data - root cause analysis, yield analysis



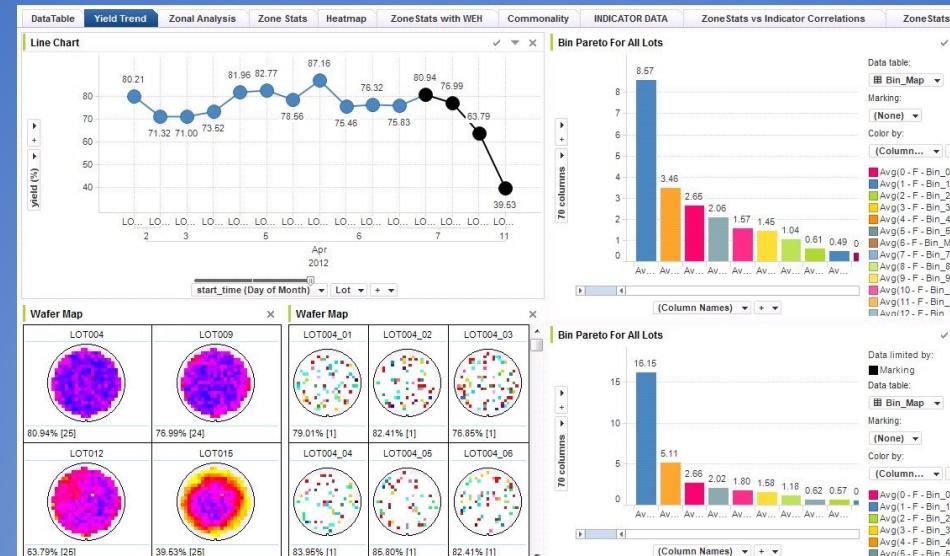
# Time-series regression/prediction/estimation

- virtual metrology
  - measure unmeasured processed materials using equipment sensor signals
  - save investment on measurement equipment, downstream applications such as process control, statistical process control, yield improvement
- yield prediction
  - predict yield (# working dies / # total dies)
  - better product quality and larger profit, business impact



# Root cause analysis using time-series anomaly detection\*

- equipment alarm root cause analysis
  - when *alarm goes off*, find responsible equipment and root causes
  - reduce equipment downtime, make *process engineers' lives easier*
- yield analysis
  - find responsible equipment and root causes for *yield drop*
  - a few % *yield improvement* brings profit increase of tens of millions of dollars!



# Difficulties with Time-series ML in manufacturing

# Data challenges

- covariate shift & concept drift

$p(x(t_k), x(t_{k-1}), \dots)$  changes over time

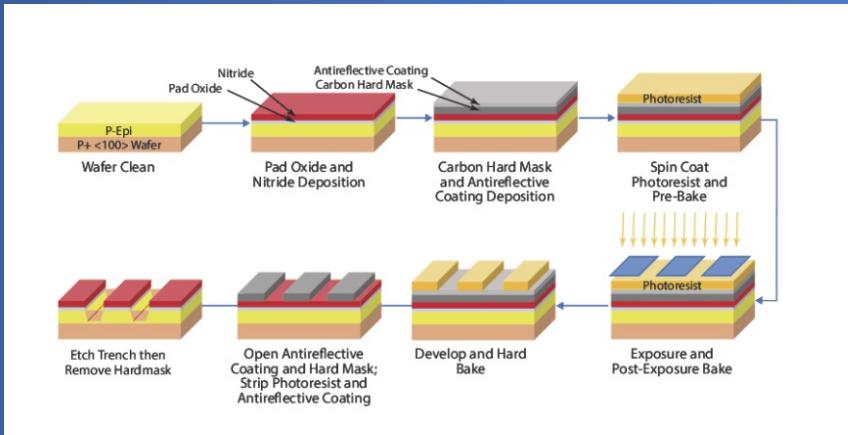
$p(y(t_k) | x(t_k), x(t_{k-1}), \dots, y(t_{k-1}), y(t_{k-2}), \dots)$  changes over time

- fat data, i.e., # features way larger than # data
- poor data quality; missing values, anomalies, wrong formats
- huge volume of data to process
- multi-modality - different types of data

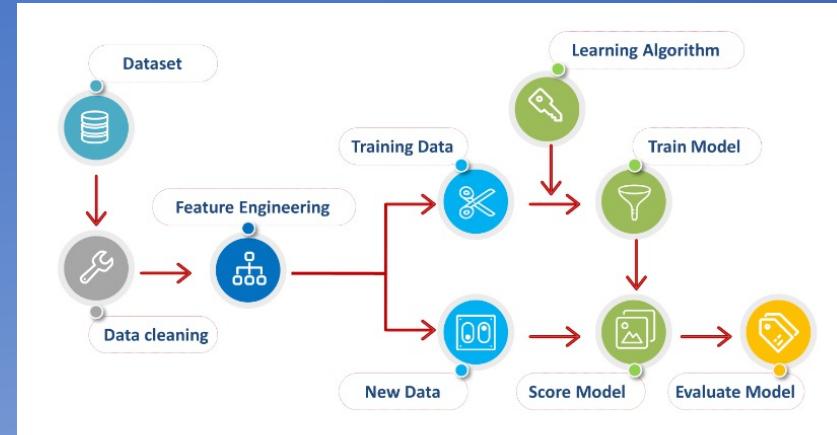
# Domain knowledge and fully home-grown algorithms

*in most cases,  
domain knowledge is critical!*

close collaboration with customers required



*off-the-shelf algorithms  
not working!*  
developing fully customized algorithms needed



# Virtual Metrology (VM)

# What is VM?

*in many cases,  
we cannot measure all  
processed materials*

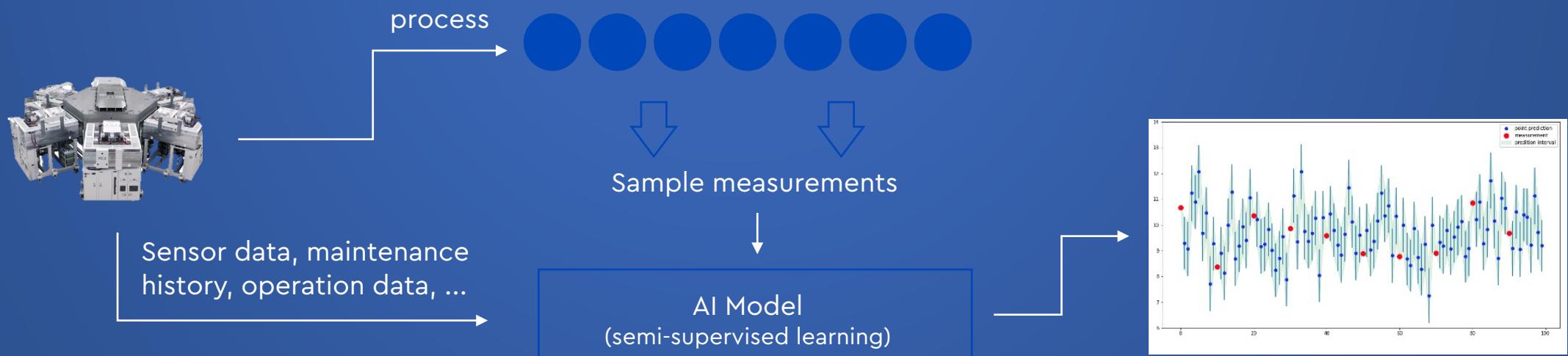
- measurement equipment is too expensive
- measuring every materials makes production slow inducing low throughput

*thus, we do sampling  
(with very low sampling rate)*

- in semiconductor manufacturing line, average sampling rate is less than 5%

## PROBLEM

- predict the measurement of unmeasured material using indirect signals
- sensor data, maintenance history, operation data, . . .



# Business Impact made by VM

## *To the best of our knowledge*

- no organization has even been successful with VM

## **Gauss Labs** **VM**

- uses online learning to cope with data drift/shift
- RMSE comparable to measurement equipment precision
- also predicts uncertainty of predictions - providing prediction reliability information

## **VM** **implications**

- measuring ALL wafers – equivalent to investing on 100x measurement equipment
- enables optimal re-allocation of limited measurement resources

# Conclusion

*supervised and unsupervised ML everywhere in industrial AI applications*

*lots of challenges*

- data challenge, domain knowledge required, need for customizing algorithms

*huge changes potentially made via various applications*

**Impacts**

- Tens of Millions of dollars by 1% yield increase
- 100x measurement equipment save by VM